

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t3752hfe-1#trpbf

(Engineering Calculation)

eTSSOP with 7 PINS REMOVED

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**TOTAL MASS (g) : 0.095666**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.003610	1000000	37735.3125		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.030596	975000	319819.84375		
		Iron (Fe)	7439-89-6	0.000753	24000	7871.10546875		
		Phosphorus (P)	7723-14-0	0.000009	300	94.0769577026		
		Zinc (Zn)	7440-66-6	0.000022	700	229.965911865		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.031380</b>	<b>1000000</b>	<b>328015.03125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.002480	1000000	25927.1289062		
		<b>External Plating Total:</b>				<b>0.002480</b>	<b>1000000</b>	<b>25927.1289062</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000806	1000000	8425.11425781		
		<b>Internal Plating Total:</b>				<b>0.000806</b>	<b>1000000</b>	<b>8425.11425781</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001031	750000	10777.0380859		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000344	250000	3595.83032227		
<b>Die Attach Total:</b>				<b>0.001375</b>	<b>1000000</b>	<b>14372.8681641</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.007460	135000	77979.3515625		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.047524	860000	496768.1875		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000276	5000	2885.02685547		
		<b>Encapsulation Total:</b>				<b>0.055260</b>	<b>1000000</b>	<b>577632.5625</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000755	1000000	7892.01171875		
					<b>TOTAL MASS (g) :</b>	<b>0.095666</b>		